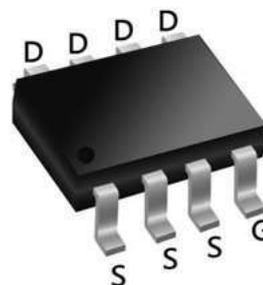


N-Ch 100V Fast Switching MOSFETs

Features:

- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

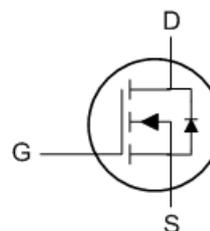


Description:

The KSCS0032 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The KSCS0032 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

SOP8 Pin Configuration



Product Summary

BVDSS	RDSON	ID
100V	24mΩ	8A

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	±20	V
$I_D@T_A=25^{\circ}C$	Continuous Drain Current ¹	8	A
$I_D@T_A=100^{\circ}C$	Continuous Drain Current ¹	6.6	A
I_{DM}	Pulsed Drain Current ²	32	A
EAS	Single Pulse Avalanche Energy ³	29	mJ
I_{AS}	Avalanche Current	24	A
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ⁴	2.7	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹ ($t \leq 10S$)	---	45	°C/W
	Thermal Resistance Junction-ambient ¹ (Steady State)	---	80	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
B _V DSS	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	100	---	---	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =8A	---	20	24	mΩ
		V _{GS} =4.5V , I _D =4A	---	23	28	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.2	---	2.5	V
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V , V _{GS} =0V , T _J =25 °C	---	---	1	uA
		V _{DS} =80V , V _{GS} =0V , T _J =55 °C	---	---	5	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V , V _{DS} =0V	---	---	±100	nA
Q _g	Total Gate Charge (10V)	V _{DS} =30V , V _{GS} =10V , I _D =8A	---	57	---	nC
Q _{gs}	Gate-Source Charge		---	8.7	---	
Q _{gd}	Gate-Drain Charge		---	14	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =30V , V _{GS} =10V , R _G =3.3Ω, I _D =1A	---	16.2	---	ns
T _r	Rise Time		---	41.2	---	
T _{d(off)}	Turn-Off Delay Time		---	56.4	---	
T _f	Fall Time		---	16.2	---	
C _{iss}	Input Capacitance	V _{DS} =25V , V _{GS} =0V , f=1MHz	---	3307	---	pF
C _{oss}	Output Capacitance		---	201	---	
C _{rss}	Reverse Transfer Capacitance		---	151	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V , Force Current	---	---	8	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25 °C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	I _F =8A , di/dt=100A/μs , T _J =25 °C	---	44	---	nS
Q _{rr}	Reverse Recovery Charge		---	25	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%
- 3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=24A
- 4.The power dissipation is limited by 150 °C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics

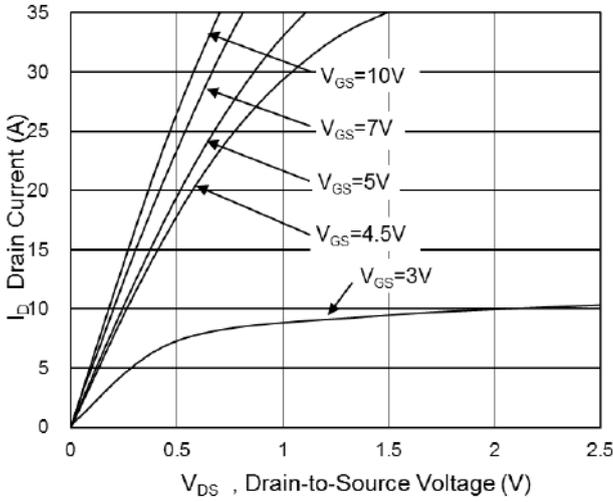


Fig.1 Typical Output Characteristics

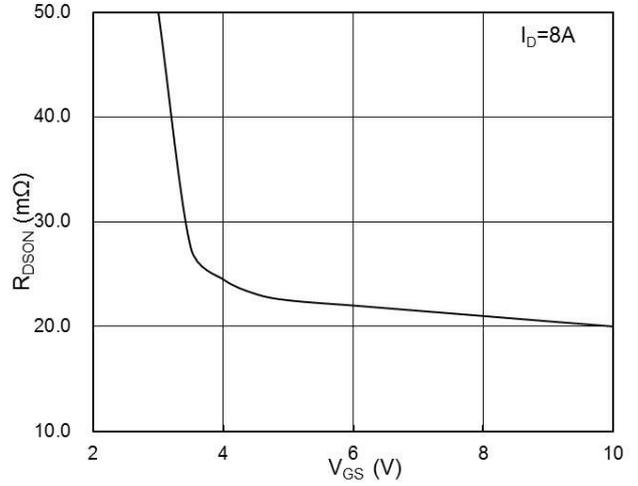


Fig.2 On-Resistance vs. G-S Voltage

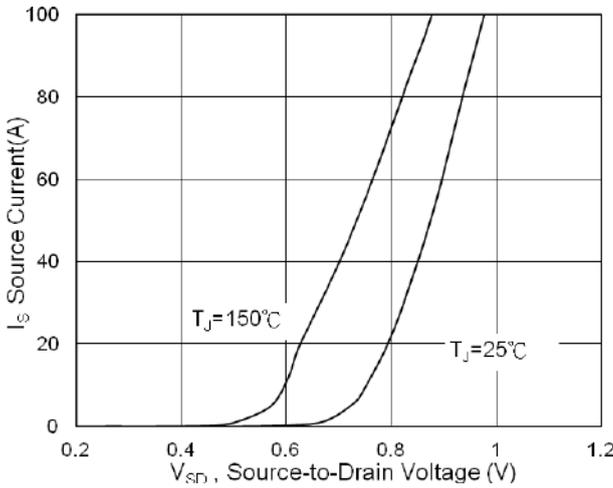


Fig.3 Source-Drain Diode Forward Voltage

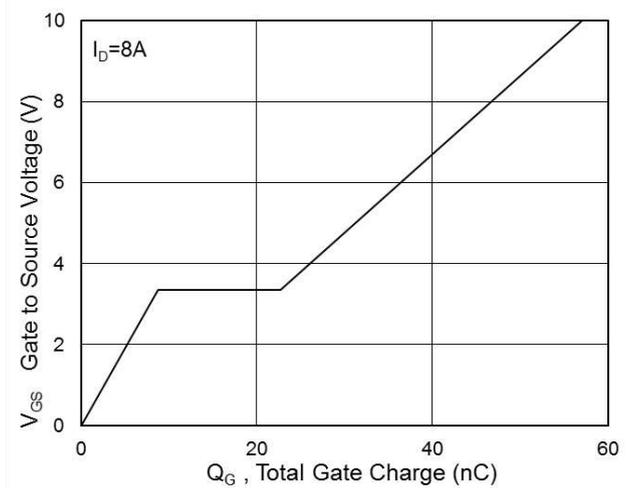


Fig.4 Gate-Charge Characteristics

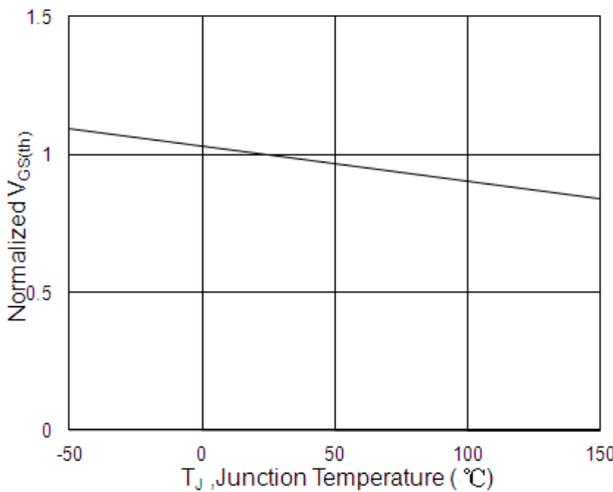


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

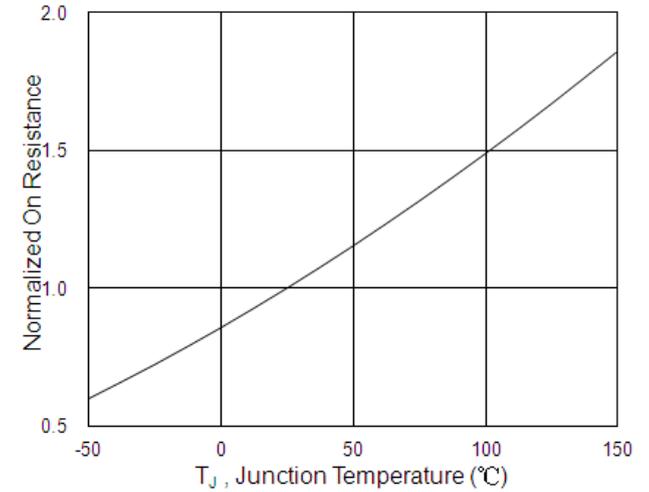


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

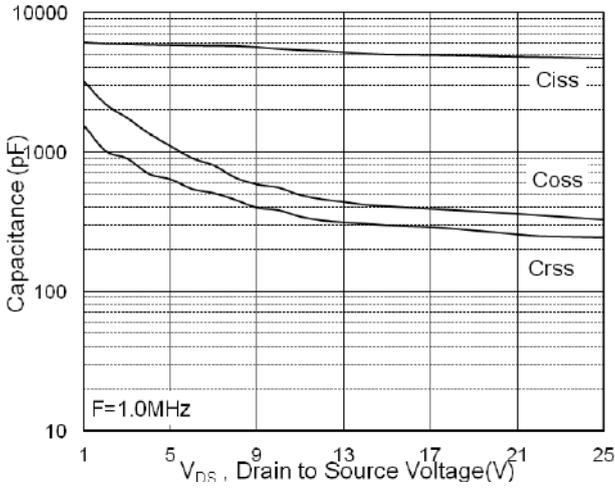


Fig.7 Capacitance

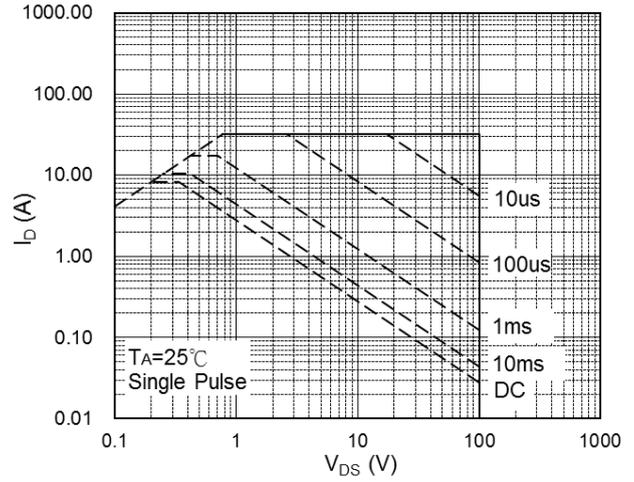


Fig.8 Safe Operating Area

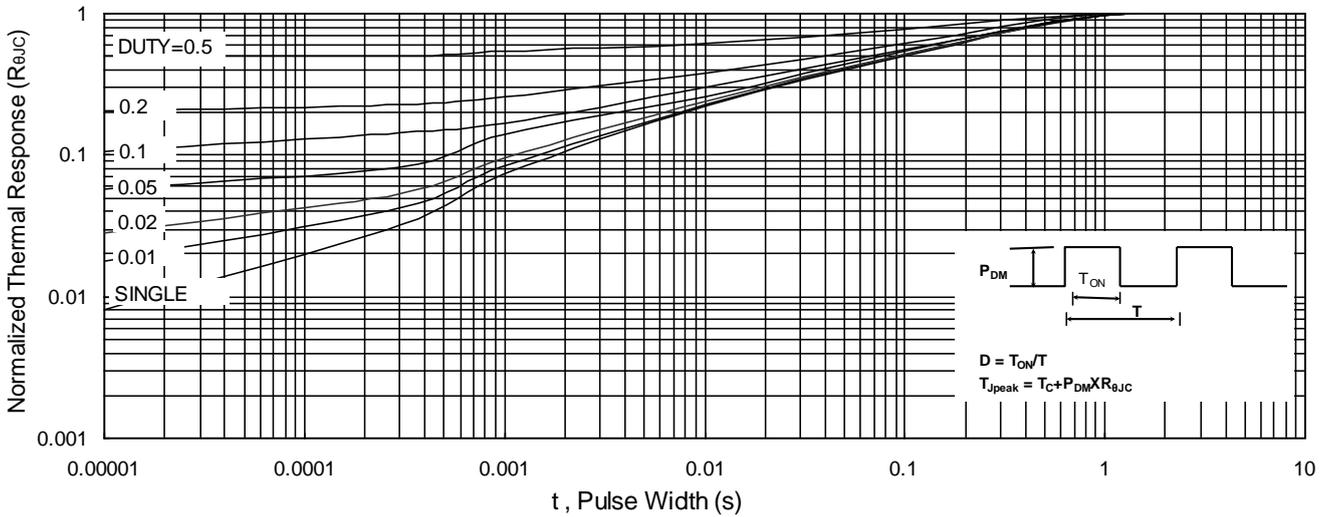


Fig.9 Normalized Maximum Transient Thermal Impedance

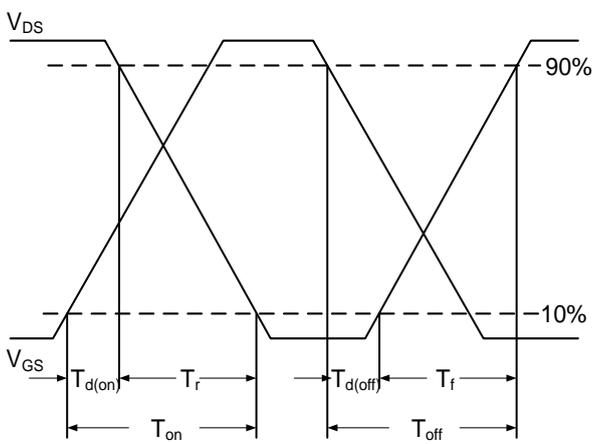


Fig.10 Switching Time Waveform

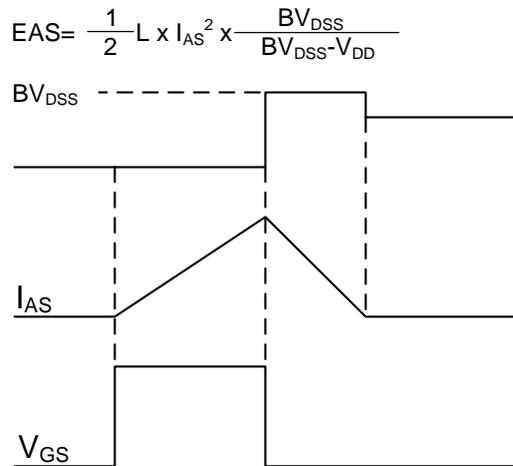


Fig.11 Unclamped Inductive Switching Waveform